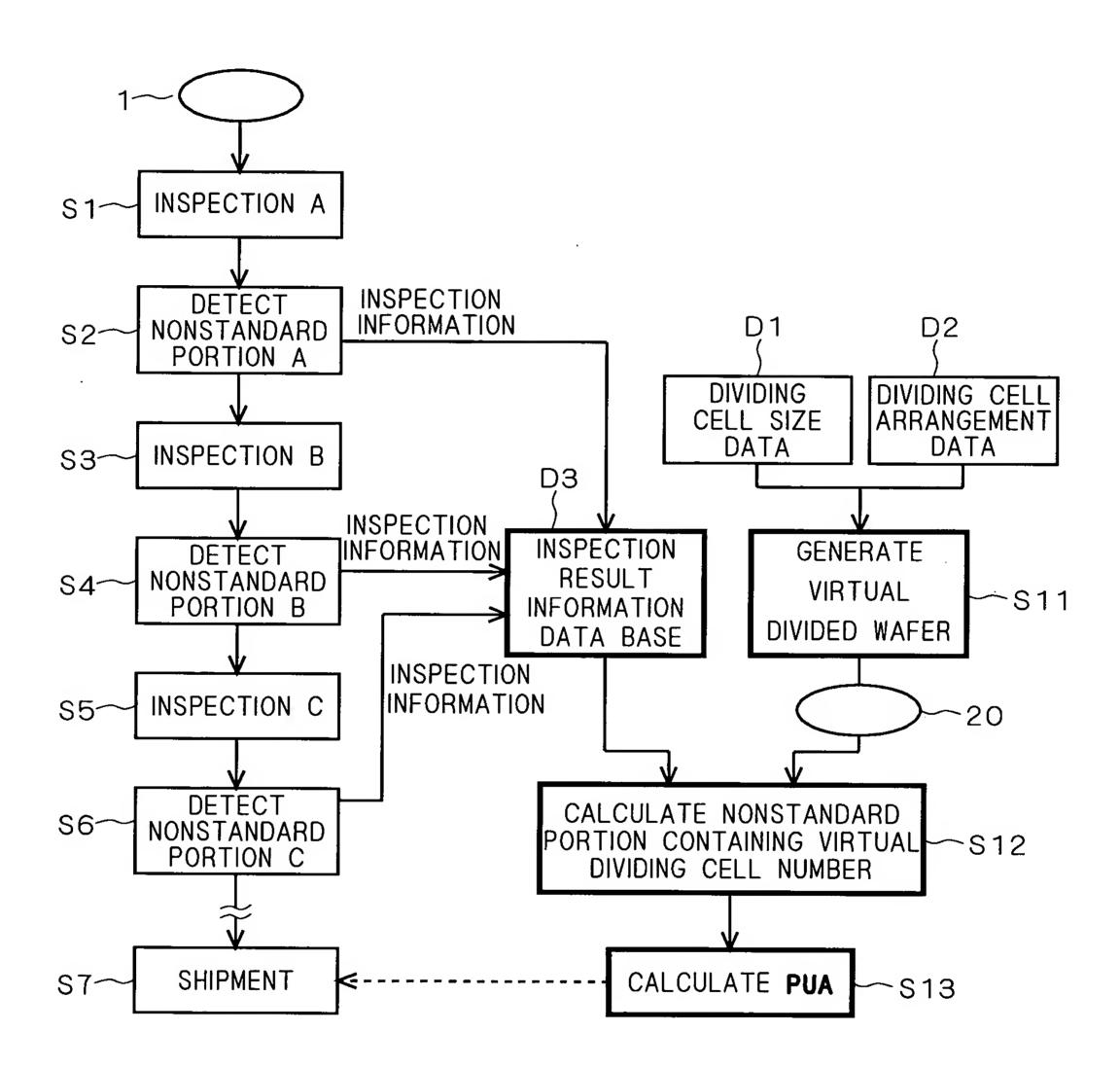
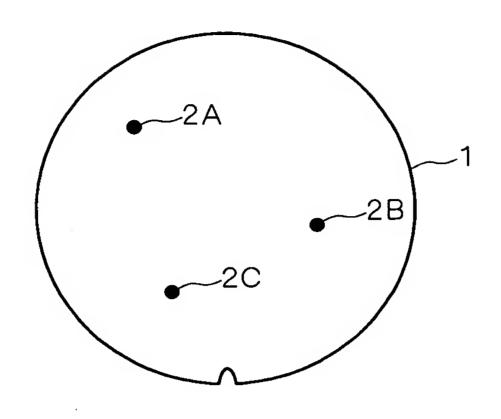
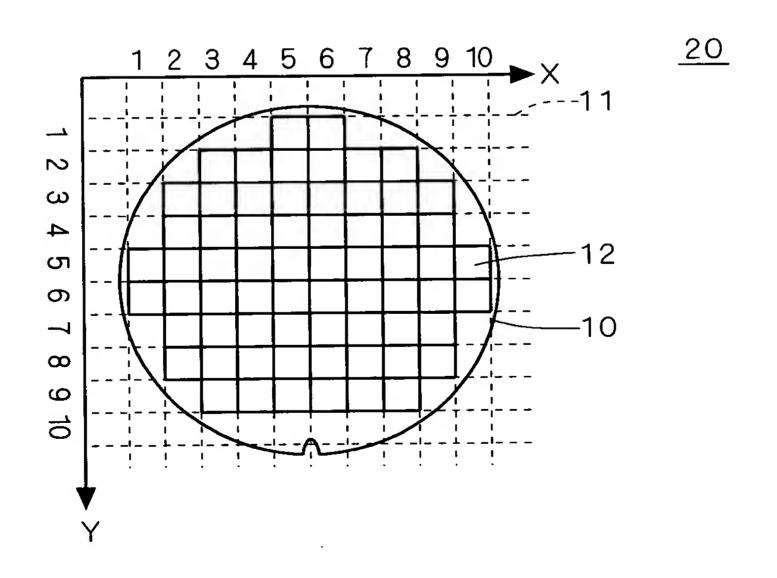
F | G . 1



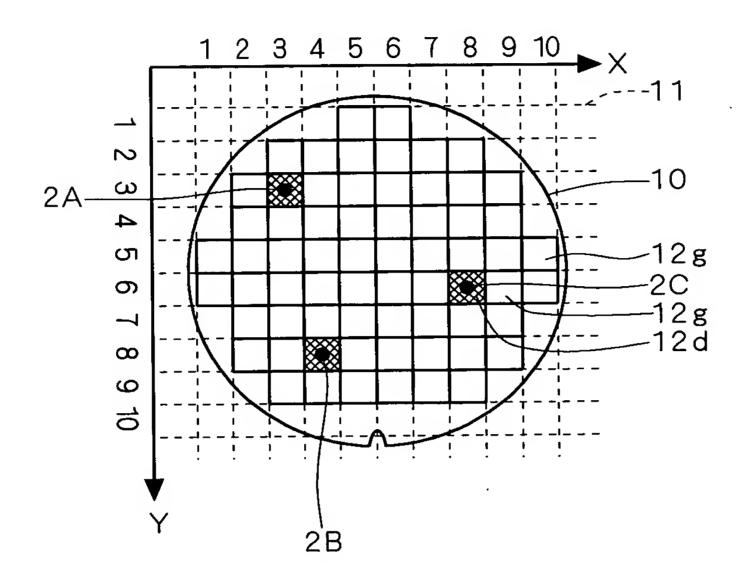
F I G . 2

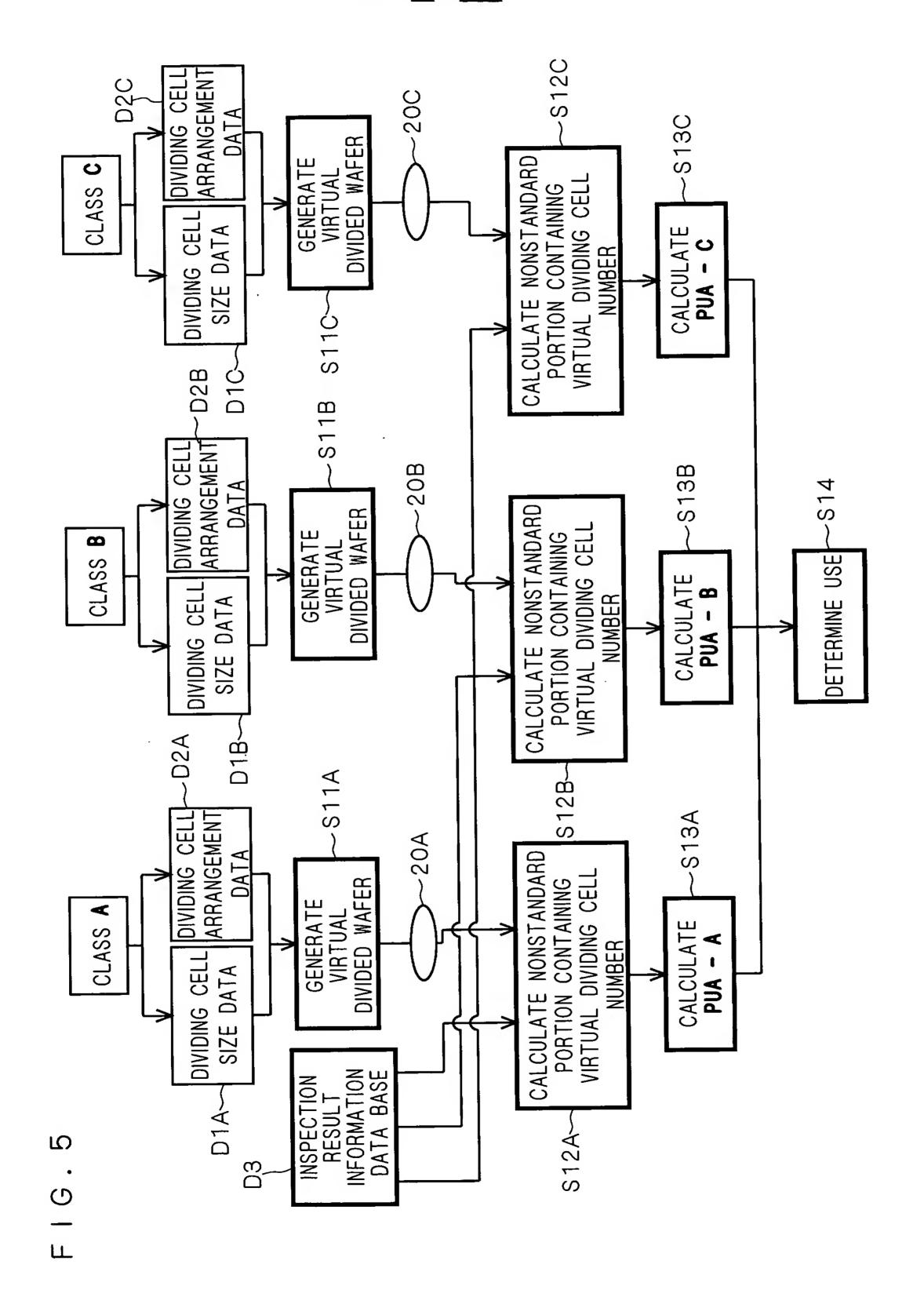


F I G . 3

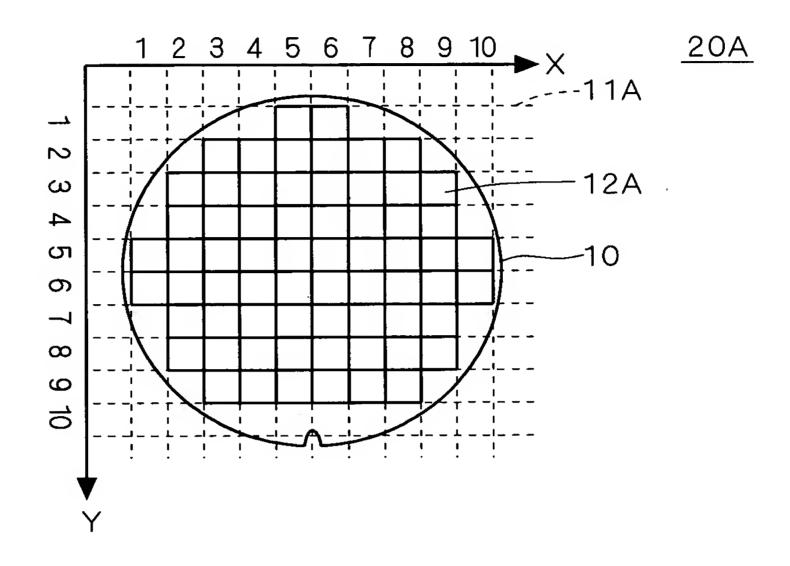


F I G . 4

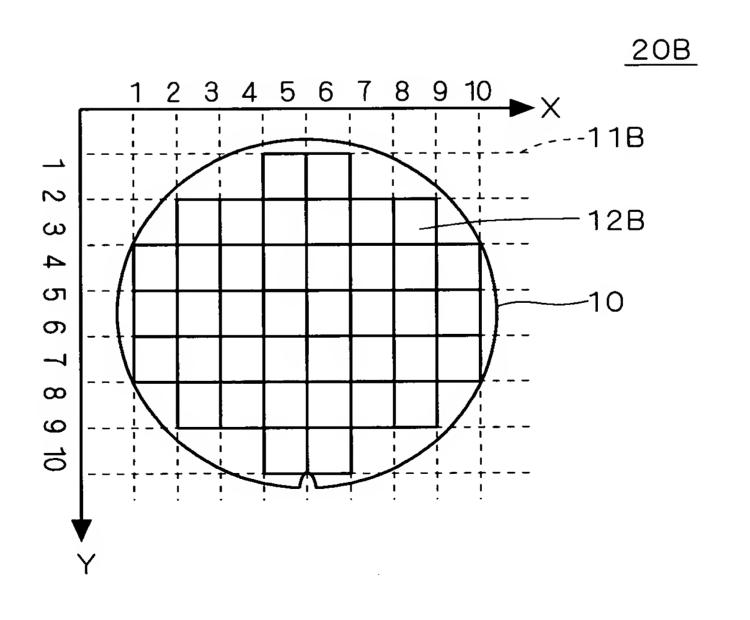




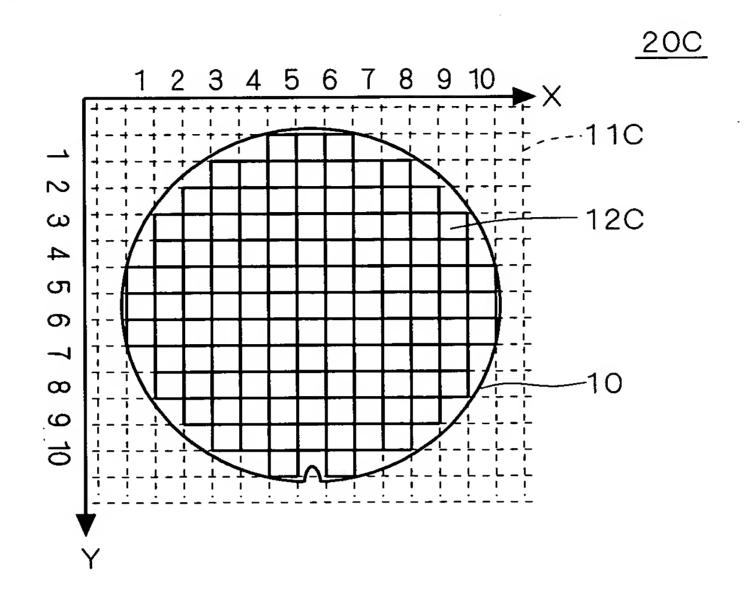
F I G . 6



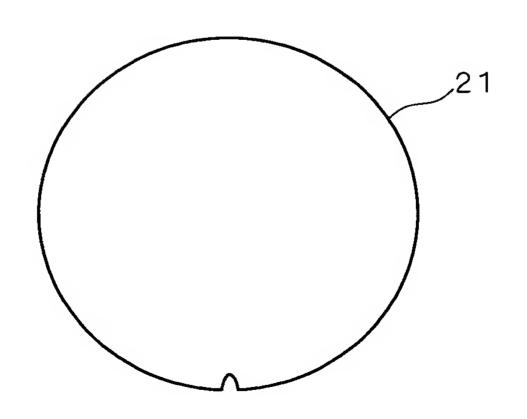
F I G . 7



F I G . 8

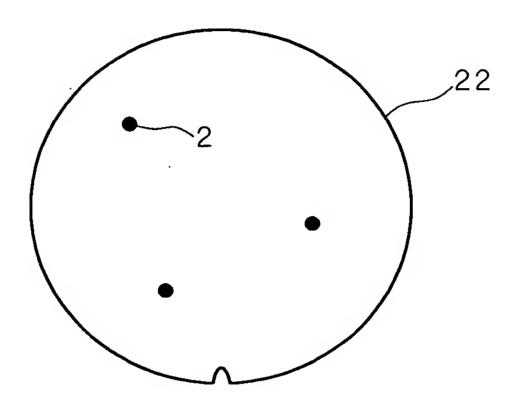


F I G . 9

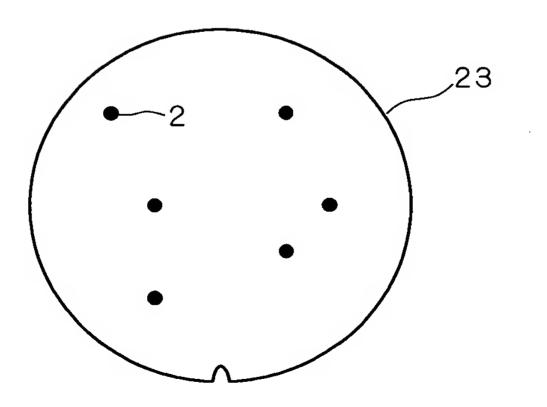


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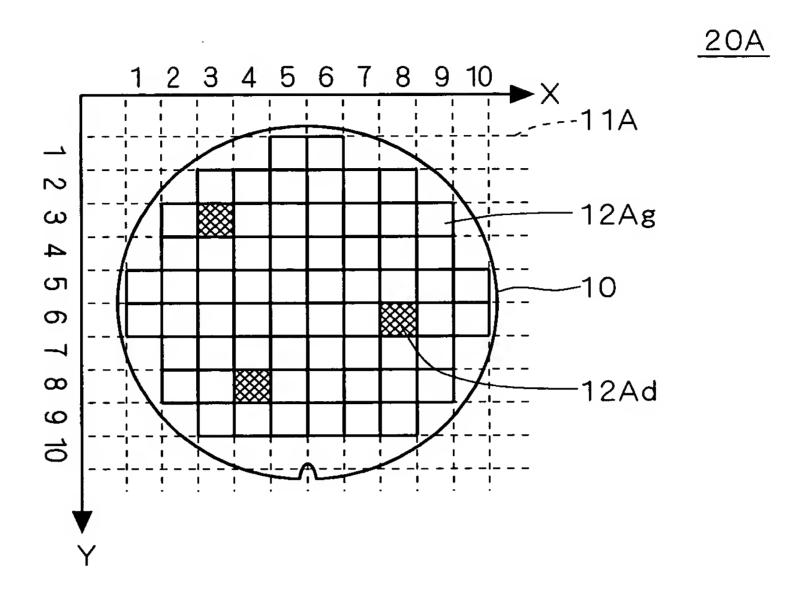
F I G . 10



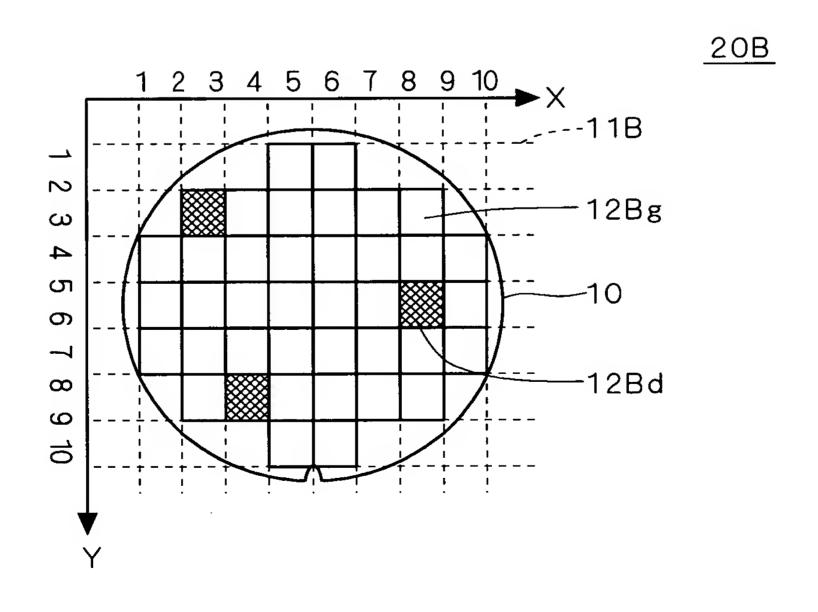
F | G . 11



F I G . 12



F I G . 13



F I G . 14

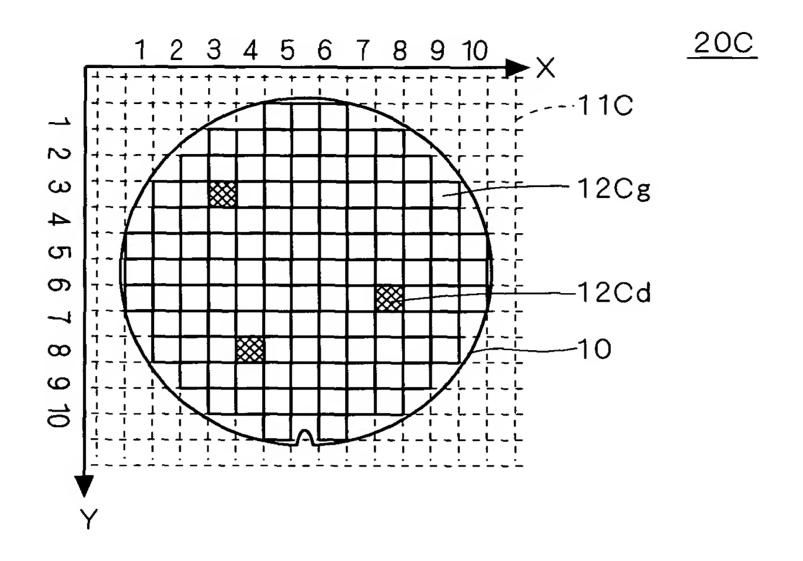


FIG. 15

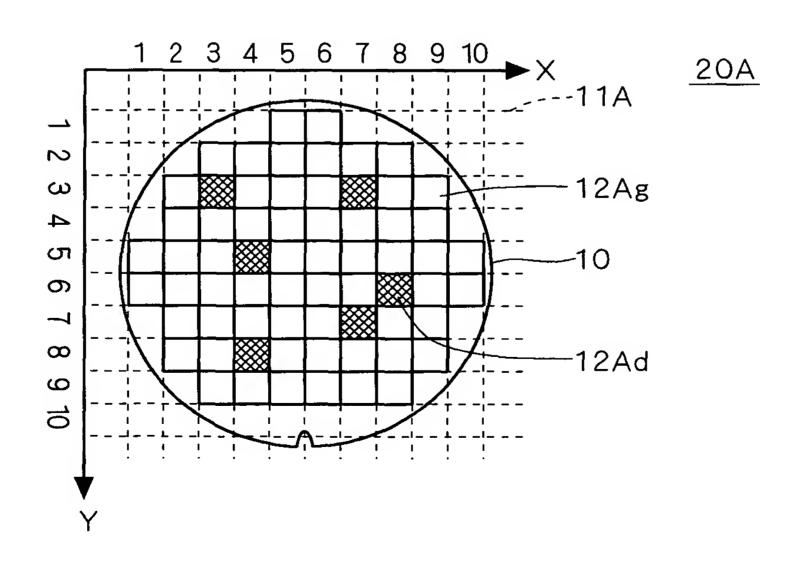
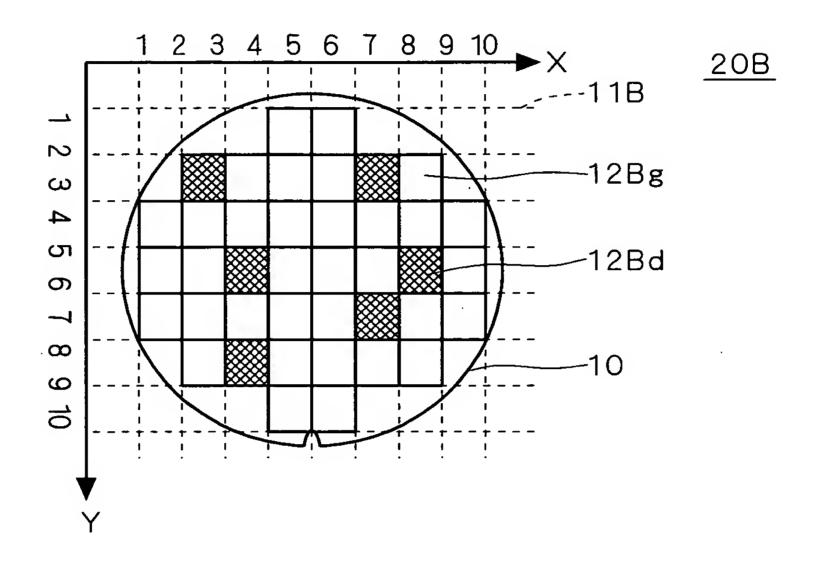
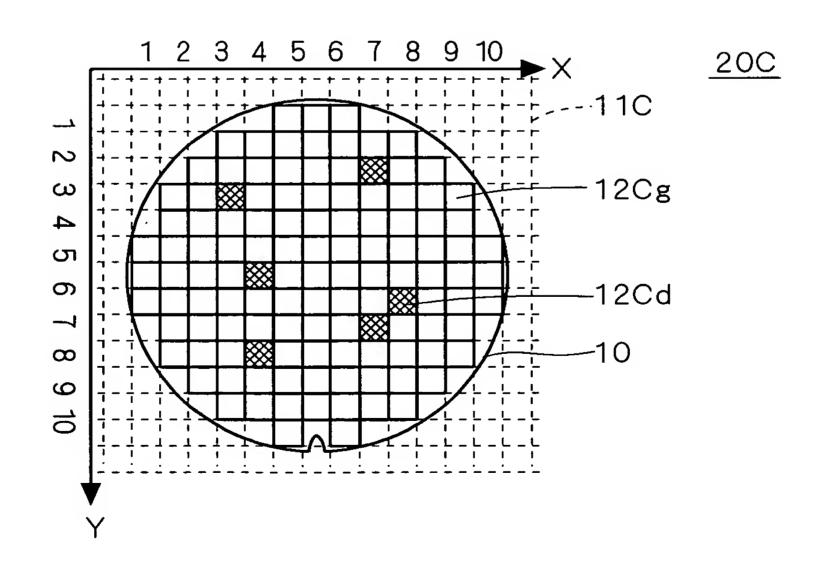


FIG. 16



F I G . 17

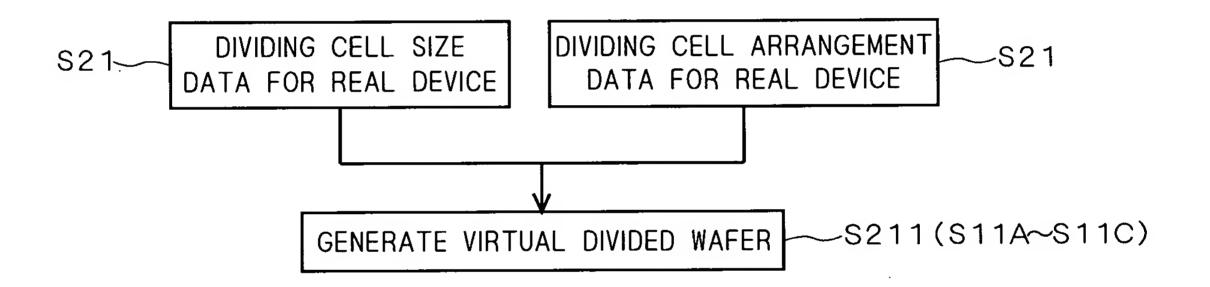


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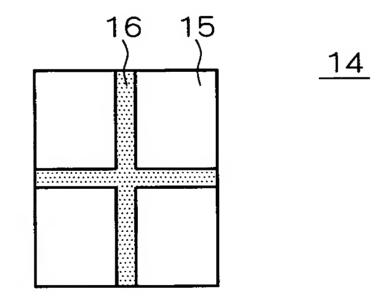
F I G. 18

EMBODIMENT NO.	INSPECTION OBJECT ITEM
3	THICKNESS OF SOI LAYER OF SOI WAFER
4	THICKNESS OF BOX LAYER OF SOI WAFER
5	LOSS OF SOI LAYER OR SOI LAYER AND BOX LAYER IN SOI WAFER
6	HILLOCK - SHAPED DEFECT OF EPITAXIAL WAFER
7	COP

F I G . 19

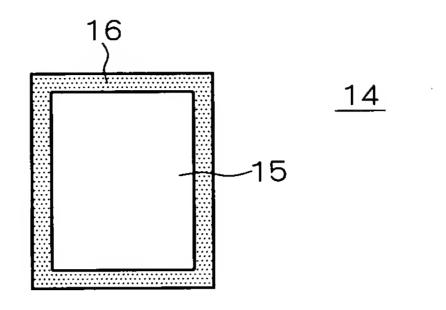


F I G . 20

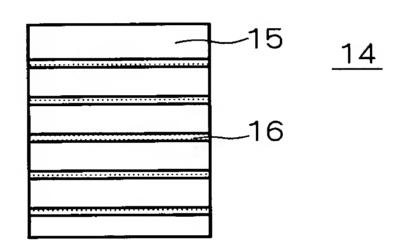


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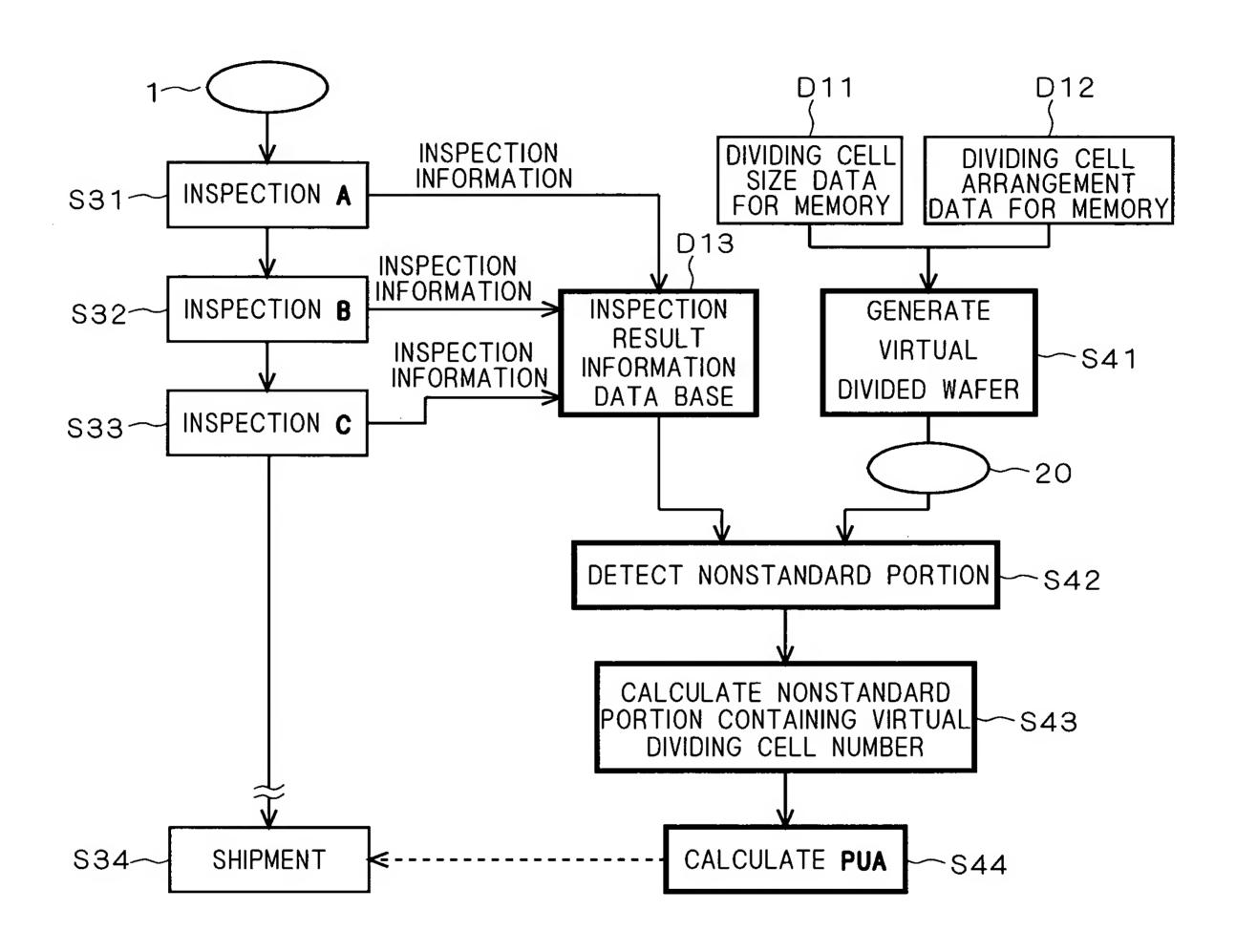
F I G . 21



F I G . 22



F I G . 23



F I G . 24

